

ABSTRACT OF THE INVENTION

A semiconductor device 30 includes a base carrier 32, an adhesive material layer 36 and an integrated circuit die 34. The base carrier 32 has a top side and a bottom side, the top side having a central area for receiving the die 34 and a peripheral area surrounding the central area. The adhesive material layer 36 is disposed on the top side of the base carrier in an "X" shaped pattern. The "X" shaped pattern includes two bisecting lines. The two bisecting lines extend well beyond the central area and into the peripheral area of the base carrier top surface. The die 34 is attached to the base carrier 32 with the adhesive material layer 36 at the central area. Even after attachment of the die 34, the adhesive material 36 extends well beyond the die 34 and the central area into the peripheral area.